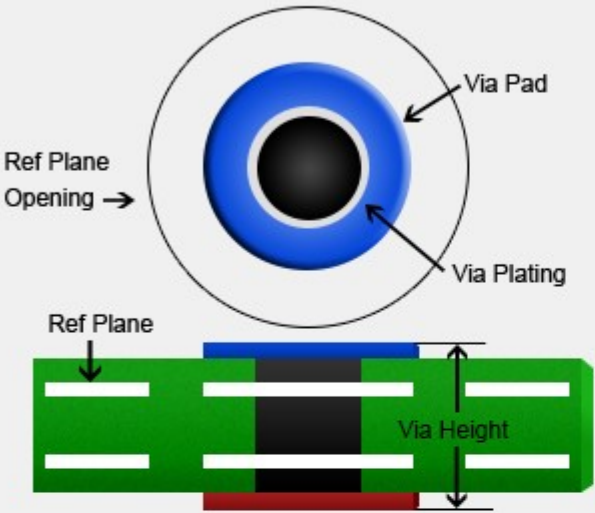


Via Characteristics



Via Hole Diameter

0.7 mm

Internal Pad Diameter

0.9 mm

Ref Plane Opening Diam

1.8 mm

Via Height

1.5748 mm

Via Plating Thickness

0.0254 mm

Options

Base Copper Weight

- ☐ 9um
- ☐ 18um
- ☒ 35um
- ☐ 53um
- ☐ 70um
- ☐ 88um
- ☐ 106um
- ☐ 142um
- ☐ 178um

Plating Thickness

- ☐ Bare PCB
- ☒ 18um
- ☐ 35um
- ☐ 53um
- ☐ 70um
- ☐ 88um
- ☐ 106um

Plane Thickness

- ☒ 35um
- ☐ 70um

Layer Set

- ☐ 2 Layer
- ☒ Multi Layer
- ☐ Microvia

Information

Power Dissipation (dBm)  
7.7583 dBm

Via Temperature  
Temp in (°C) = 42.0  
Temp in (°F) = 107.6

Unit

- ☐ Im
- ☒ Me

Sub

Mate

Er

4.6

Tem

Temp

Amb

Temp

Pri

IPC-2152 with modifiers mode

Via Capacitance

0.4021 pF

Via DC Resistance

0.00051 Ohms

Power Dissipation

0.00597 Watts

Via Inductance

1.0070 nH

Resonant Frequency

7909.163 MHz

Conductor Cross Section

0.0579 Sq.mm

Via Impedance

50.040 Ohms

Step Response

22.1352 ps

Via Current

3.4365 Amps



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